

WP10 – status report



VNIVERSITAT
ID VALÈNCIA



CSIC

CONSEJO SUPERIOR DE INVESTIGACIONES CIENTÍFICAS

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With inputs from all WP10 groups

AIDAinnova 3rd annual meeting, Catania, March 21st



WP10 parallel session, with reports from all groups:

<https://indico.cern.ch/event/1307202/sessions/502041/#20240320>

Thanks to all speakers for their contributions, and for providing summary slides



WP10 goal: make sure that support, cooling and services do not limit the material budget of the next generation of vertex detectors and silicon trackers

20 years ago:

Full rad-hard, high-rate pixel+strip system $\sim 0.4-1.8 X_0$

Note: Silicon contributes: $10 \times 2 \times 300 \mu\text{m} \sim 0.06 X_0$

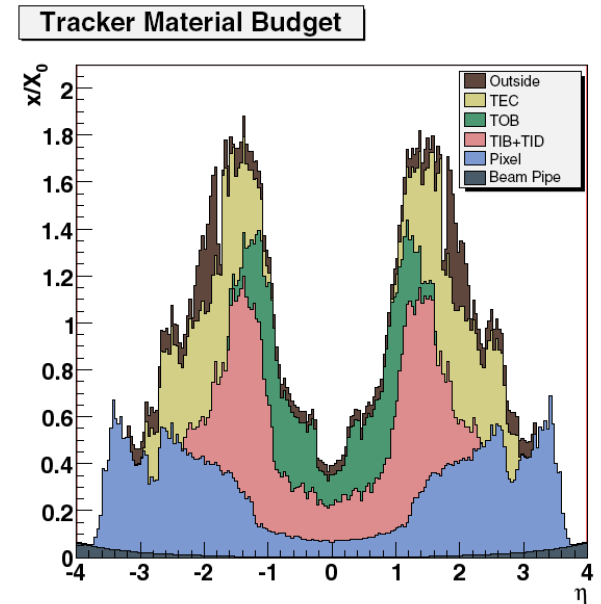
Today:

WP5&6: active Silicon reduced to $< 50 \mu\text{m}/\text{layer}$

Can we reduce all non-active material too?

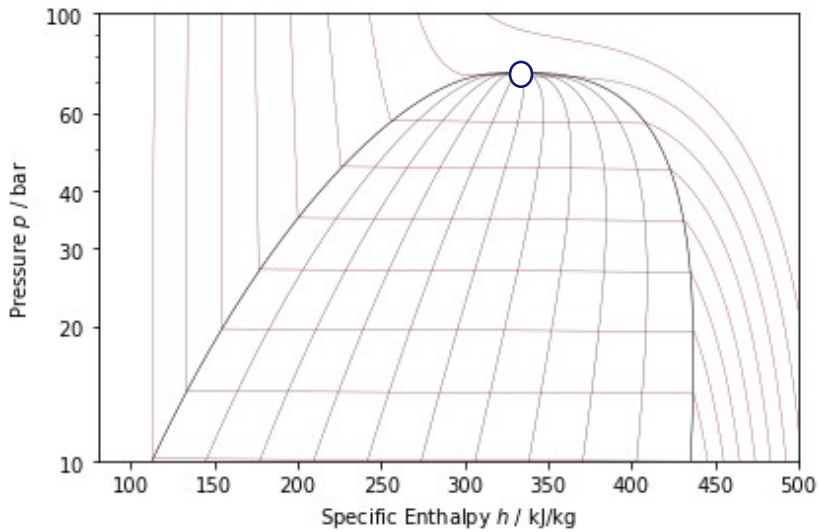
The answer has to be yes, but this requires work on:

- new coolants and new cooling concepts
- novel materials/techniques
- further integration of active material, support, cooling and services
- more precise characterization of thermo-mechanical performance

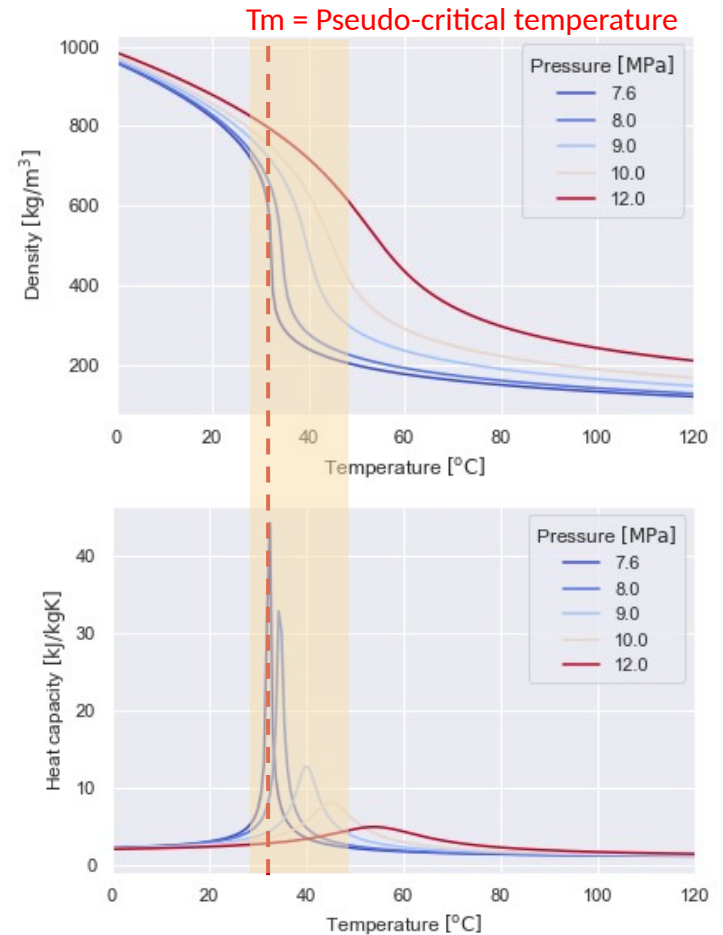


Super-critical coolants (CERN)

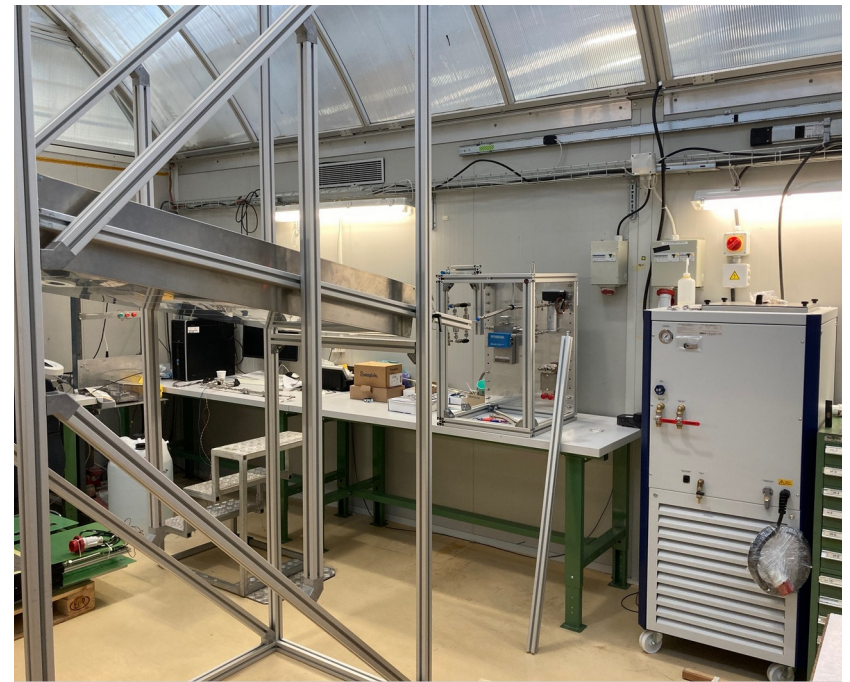
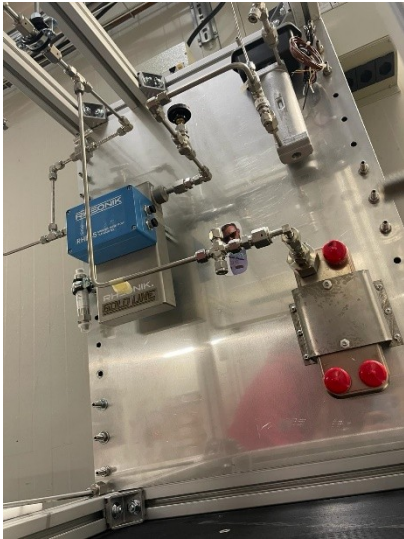
- Above critical value: change is continuous
 - $T < T_c$ liquid-like fluid
 - $T > T_c$ vapor-like fluid
- Critical point of carbon dioxide: 74 bar, 31 °C
- Super-critical Krypton possible ultra-cold solution



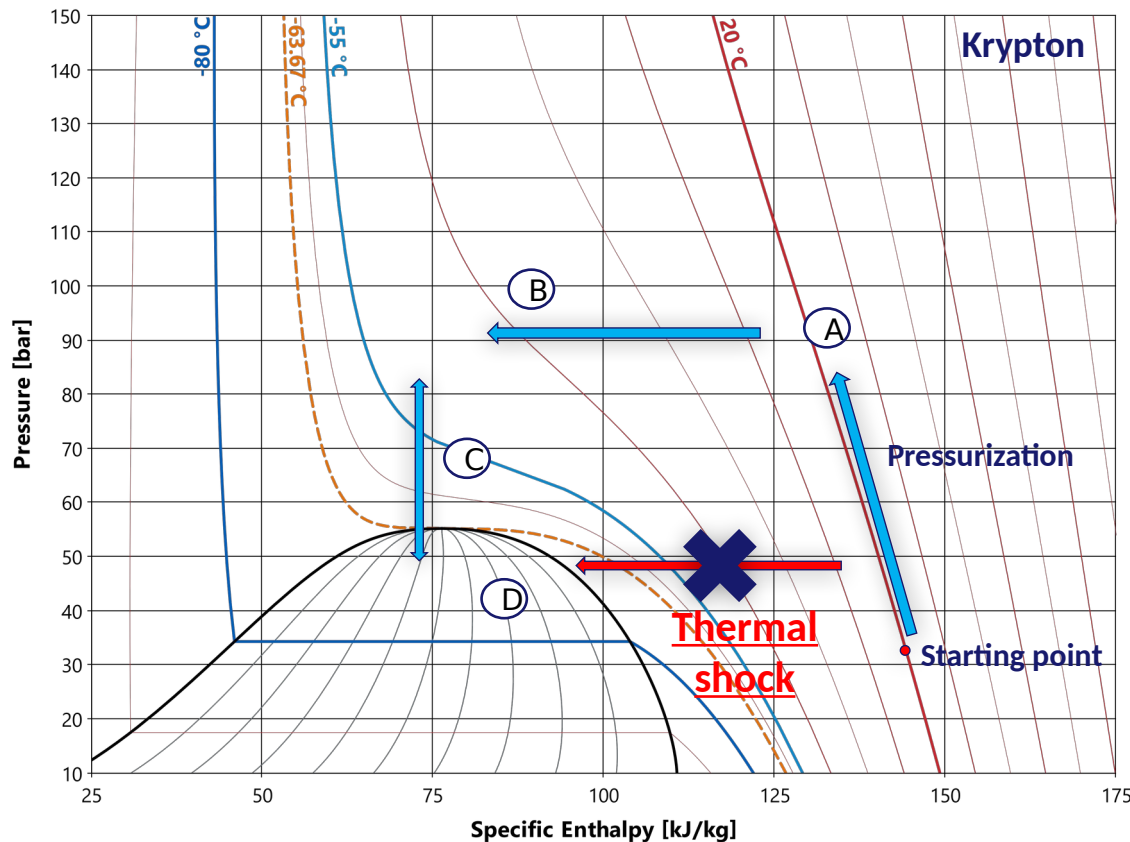
Temperature of interest for room temperature detector cooling (+31 to +45 °C)



Status of CERN test rig



- Challenges with Krypton cooling: start cooling cycle without thermal shock
- Conceptual solution developed, tests foreseen



- Starting temperature (20 degC) in gas/supercritical phase



Four different scenarios to be investigated:

- Startup (A)
- Supercritical cooldown (B)
- Supercritical operation (C)
- Transcritical operation (D)

Status of test rig (C. Pedano, CERN)



Task	CO2 Timeline	Krypton Timeline
April-May 2024	Setup construction Development of DAQ	Tests at NTNU
June 2024	Commissioning	
Summer 2024	Measurement campaign	Tests at CERN

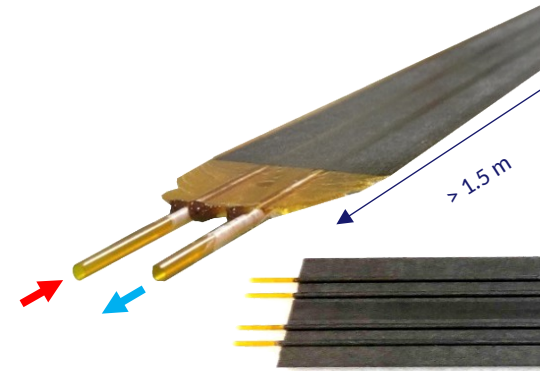
Answer essential questions in AIDAInnova:
Stable operation at super-critical CO2?
Viable operation cycle for super-critical Krypton?

- Ultra-light structures with integrated cooling

Carbon cold plate with embedded Kapton pipe

Purpose:

- Technology compatibility with high-pressure boiling coolants.
- Produce large surfaces cold plate (CP) for high-pressure boiling coolants.
 - i.e. evaporative CO₂ and new coolants (Krypton, ...)

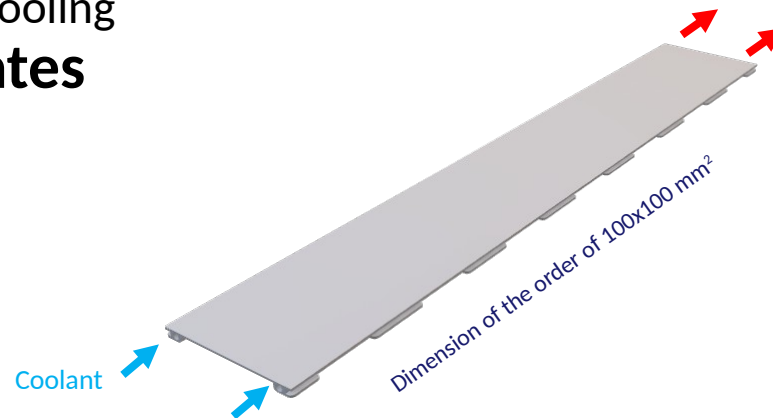


- 3D-printed structures with integrated cooling

AM Ceramic & Metal cold plates

Purpose:

- Generation of new standards to produce micro-structured cold plates produced by additive manufacturing, (ultra-thin wall).



- **Achievement:** Established low-mass cold plate design with embedded Kapton pipes adapted and tested successfully with evaporative CO₂.

Article under internal review: *On-detector cooling systems based on low-mass carbon dioxide evaporators: cold plates with embedded Kapton tubes* (D. Hellenschmidt, ...)

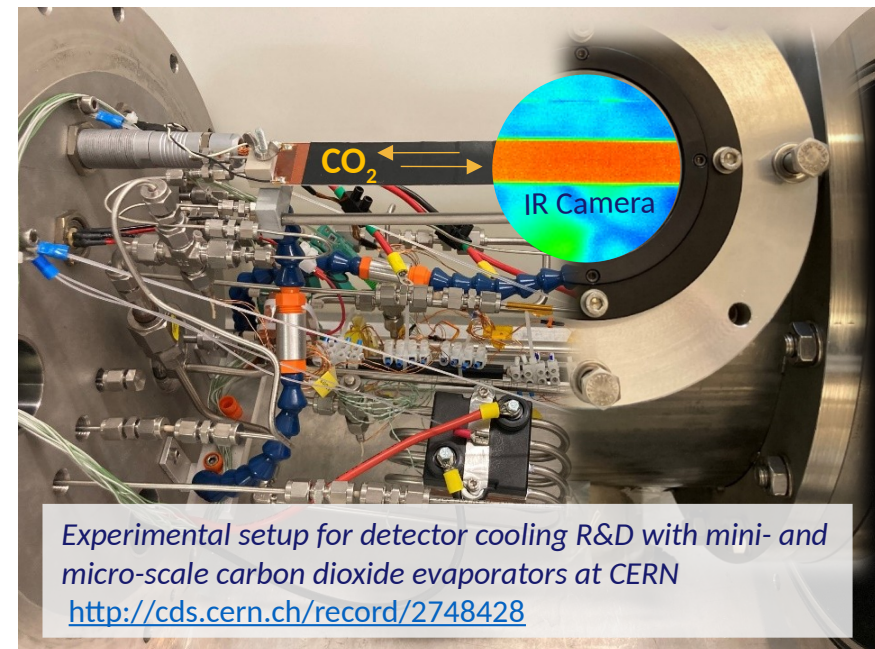


CERN EP R&D WP4



D. Hellenschmidt
M. Angeletti

Experimental setup



Experimental setup for detector cooling R&D with mini- and micro-scale carbon dioxide evaporators at CERN
<http://cds.cern.ch/record/2748428>

- Know-how transferred to Workshape industrial partner
- **ONGOING:** 1.5m cold plate production (ITS2 like)
- Issues reproducing ALICE cold plates due to resin differences
- Cold plates manufacturing by end of April 2024.

NEXT: 1.5m cold plate
(High-pressure resistance)



CERN EP R&D WP4 

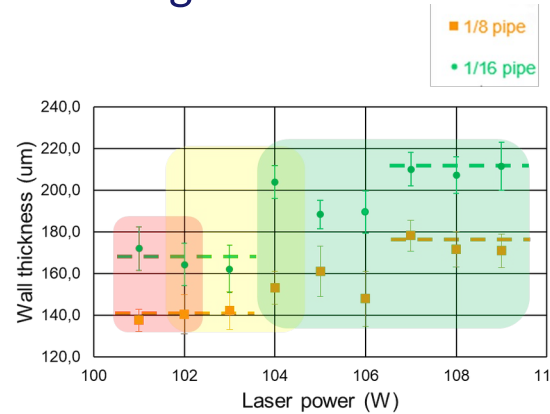
CERN Knowledge Transfer



3D integrated cooling circuits

- Investigation on the smallest leak-tight wall thickness for Al alloy

- 160 um 1/8" pipe
- 190 um 1/16" pipe

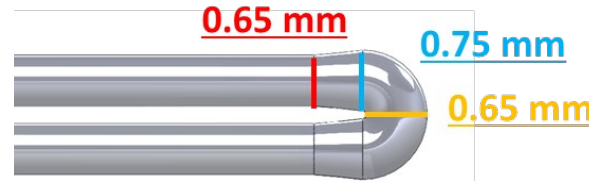


Updates: CSEM

- The printing limits of AlSi12 material have been thoroughly understood.
- KOVAR powder has been purchased; and printing capabilities with KOVAR material is currently under study.

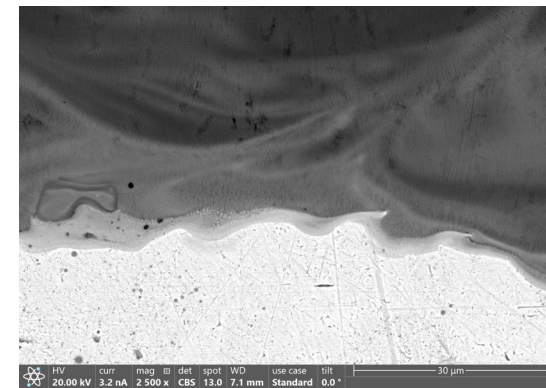
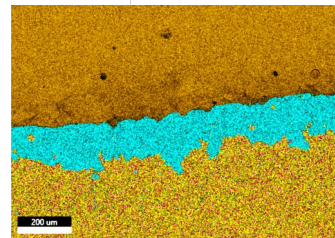
- Investigation on the smallest 180° curvature design size to remove powder

- Pipe length: 85 mm
- Pipe hole: 0.44 mm



- Multi-material printing

- Aluminium-kovar with silver inter-layer
- Thermal cycling to be tested



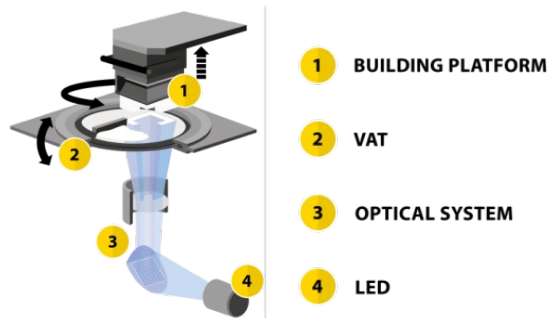
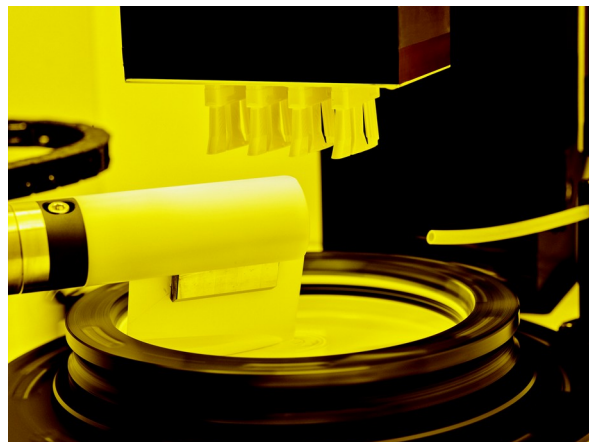
3D integrated cooling circuits in the structure

• Materials and technologies:

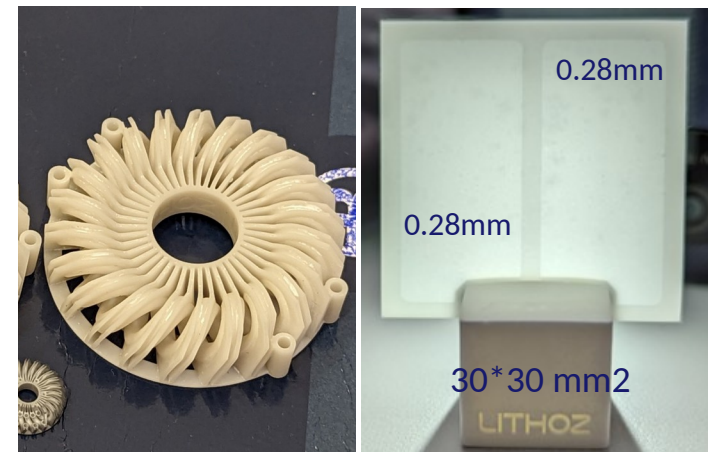
- **AM:** Lithography-based Ceramic Manufacturing (LCM) technology.
- **Ceramics:** Aluminum oxide (Al_2O_3),
ONGOING: Aluminum nitride (AlN), Polymer-Ceramic composites.
- **Aim:** Define the optimal geometrical features attainable
e.g. Minimum achievable wall thickness of pipes/plates,
Flatness optimization (Firing step, 1500-2000 C, warping effect).

Updates: Lithoz

- The printing limits of Al_2O_3 material have been thoroughly understood.
- Additional samples in AlN are in production for future irradiation test campaign.
- Optimization of cold plate flatness investigation currently on going



Blue light cures the photosensitive formulation



- **Analysis, experimental tests:**

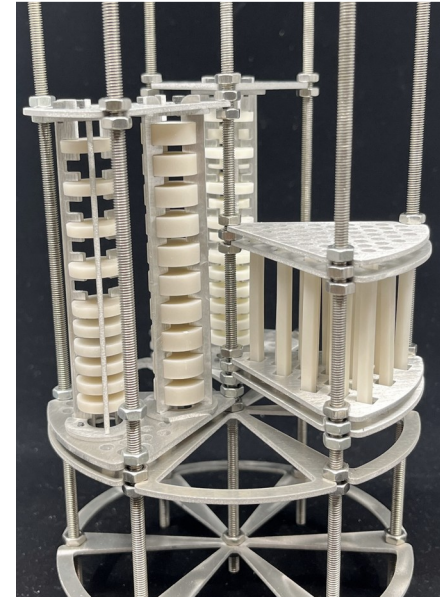
- Metrology, mechanical characterization tests (CERN)



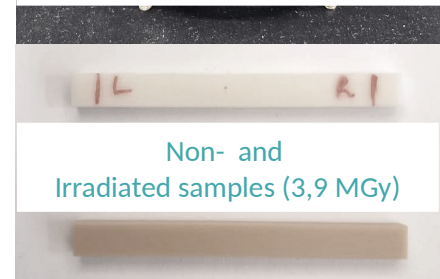
Material properties investigation

Updates: CERN

- Geometrical limits for AlSi12, Al₂O₃ and AlN have been identified.
- First irradiation campaign and characterization tests completed for Al₂O₃ and AlN. No relevant changing in material properties (thermal conductivity, Flexural modulus/strength) have been noticed.

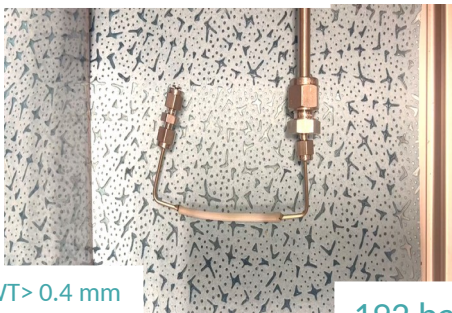


Aluminium cradle for irradiation test campaign



Non- and irradiated samples (3,9 MGy)

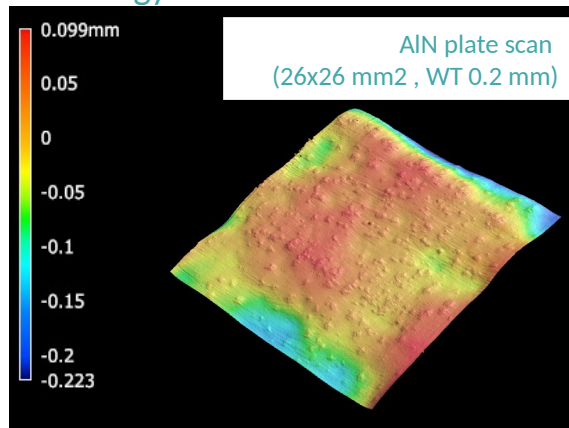
AlN, OD 3,2 mm, WT 0.3 mm



WT > 0.4 mm
P > 250 bar

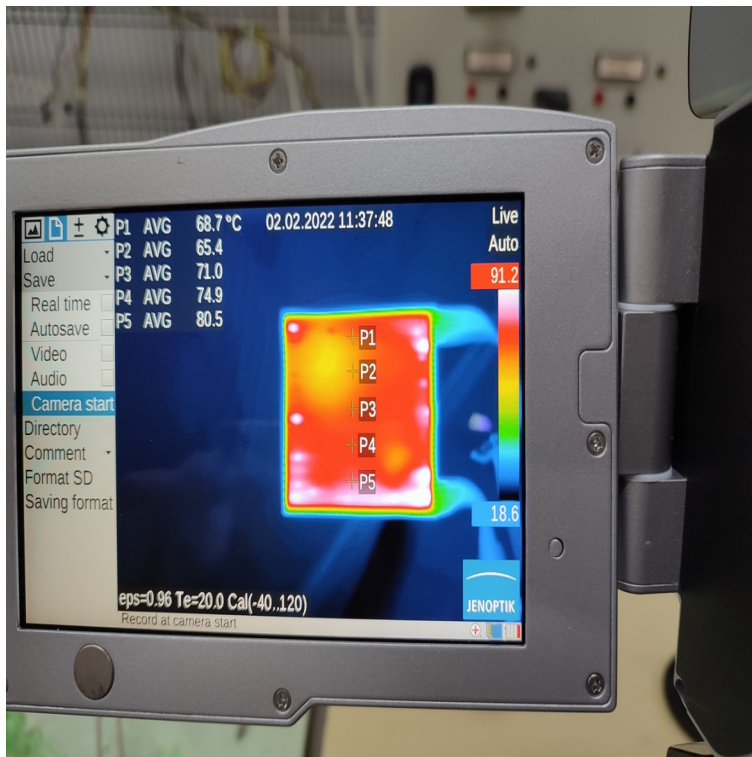
192 bar

Metrology



NEXT:
5 MGy irradiation campaign

Pyrex (300 μm)+ Silicon sandwich, glue Masterbond EP30TC



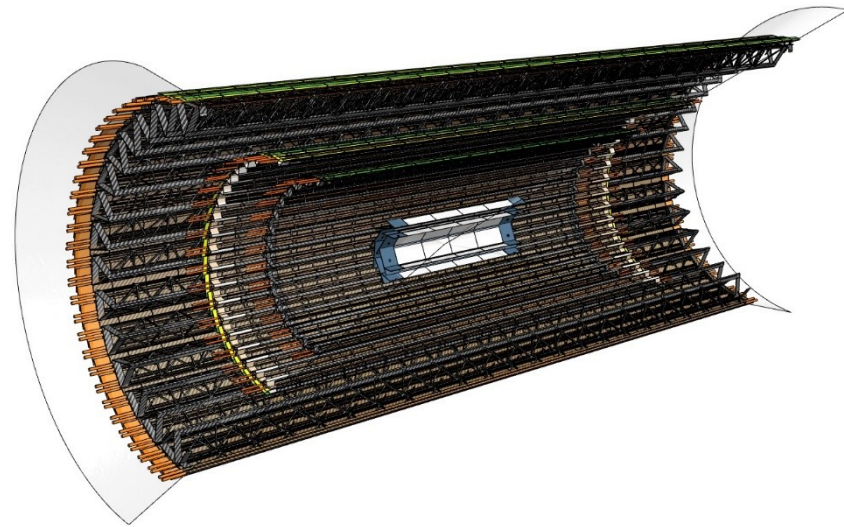
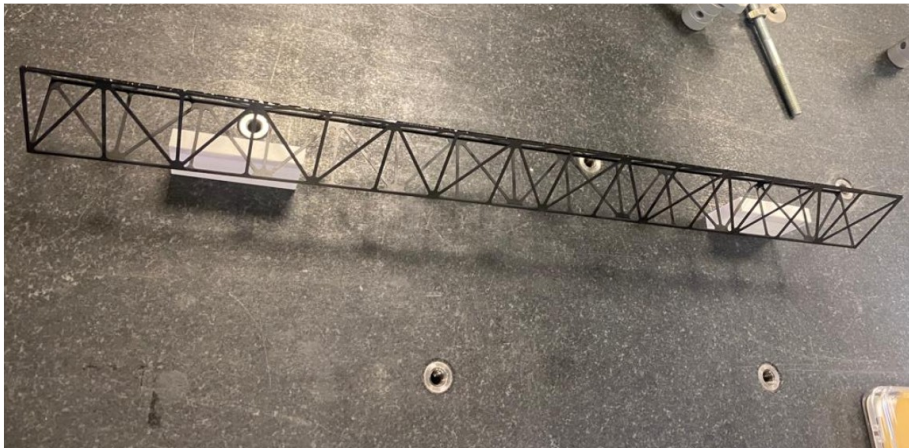
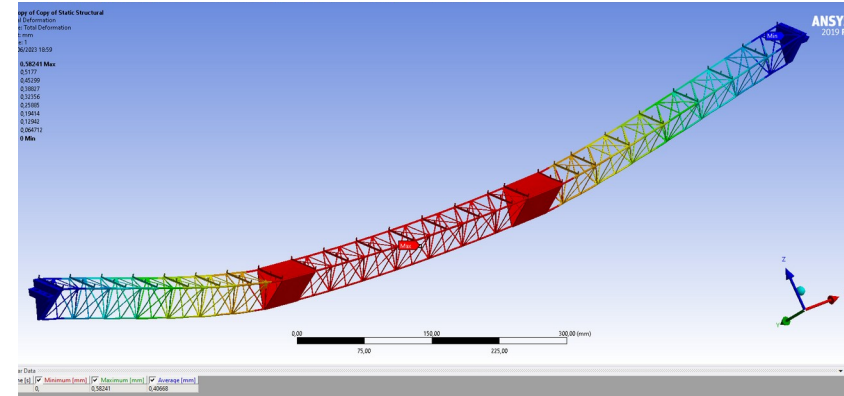
Heaters to simulate power load up to 97 W

Cooling fluid at 5°C with 0.33 kg/min flow rate

Calibrated infrared camera to monitor temperature: kept to 72°C

Truss structure for outer layers of Belle 2 silicon tracker and future CEPC experiment

Measurements, simulations on prototypes and complete engineered design

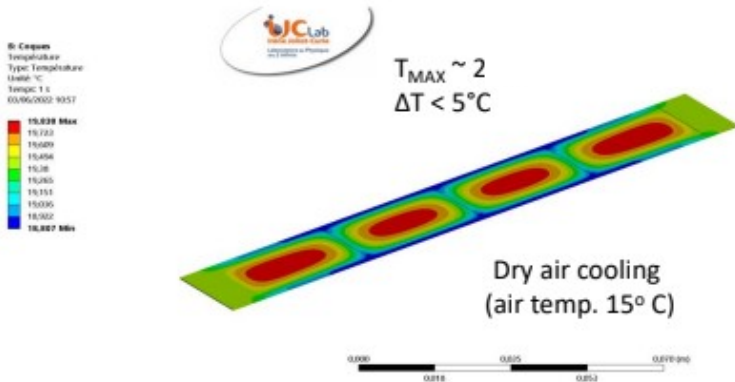
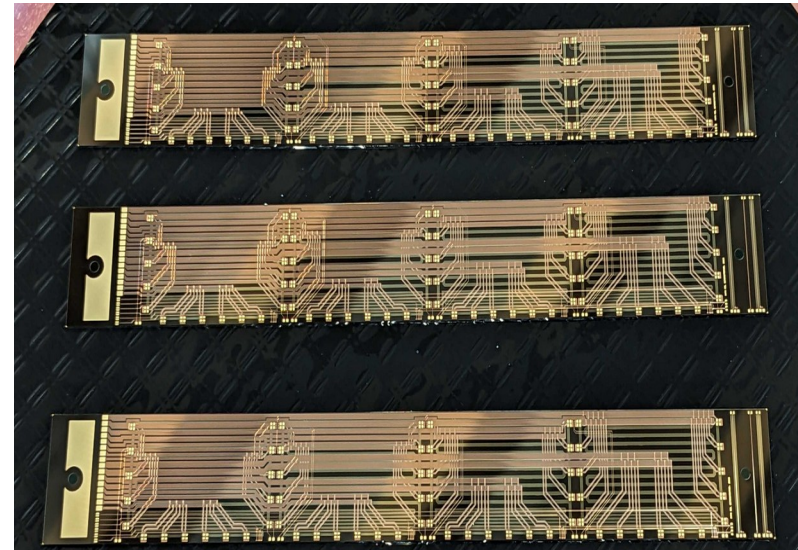


Thin multi-CMOS-chip Silicon structures for Belle 2 upgrade

Thermo-mechanical iVTX demonstrator delivered by IZM to Valencia/Bonn

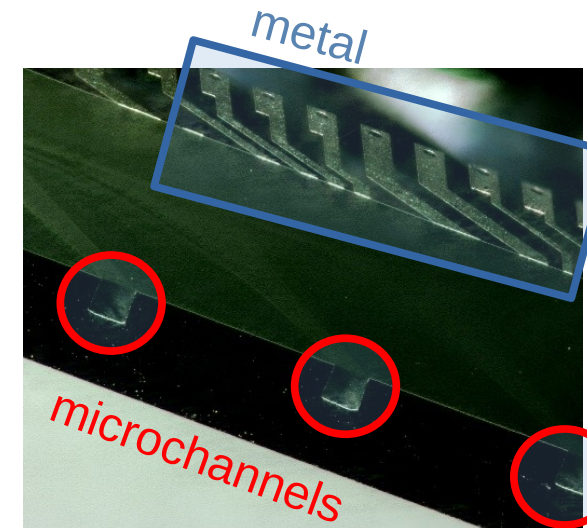
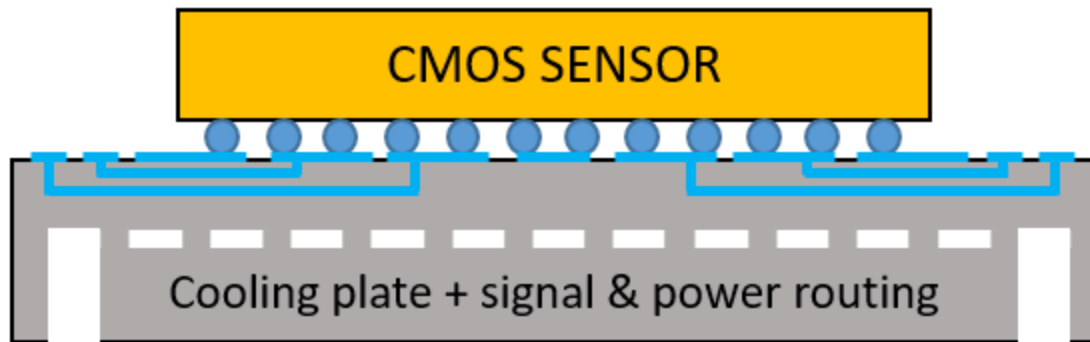
Thermal simulations (IJCLab Paris)
to be validated against lab tests

Basis for FE analysis of future
collider cooling strategies (C. Orero, IFIC)



Micro-channel production capacity at CNM

- Integrated cooling channels and metal system with different bonding techniques
 - Pre-processing (i.e. micro-channels first, metal/CMOS last)
 - Anodic (glass-Silicon) bonding post-processing
 - Optimizing eutectic wafer bonding technique



Wire bonding tests show integrity of metal after wafer bonding

Steps on the way to CMOS-compatible integrated microchannels



MPG HLL Status

- ▷ MPG HLL is working on the installation of a process line for
 - ↳ Post processing of up to 200 mm CMOS wafers
 - ↳ Fabrication of actively cooled interposers with micro-channels and TSVs
 - ↳ Low temperature direct bonding
 - ↳ Hybrid bonding of post-processed CMOS wafers or single CMOS chips to sensors wafers

- ▷ Current status
 - ↳ The clean room of MPG HLL was relocated to a new and larger building
 - ↳ Tests with equipment manufacturer finished, tool configuration done, purchasing in progress
 - ↳ Relocated equipment currently in the hook-up phase, qualification to follow



MPG HLL Status



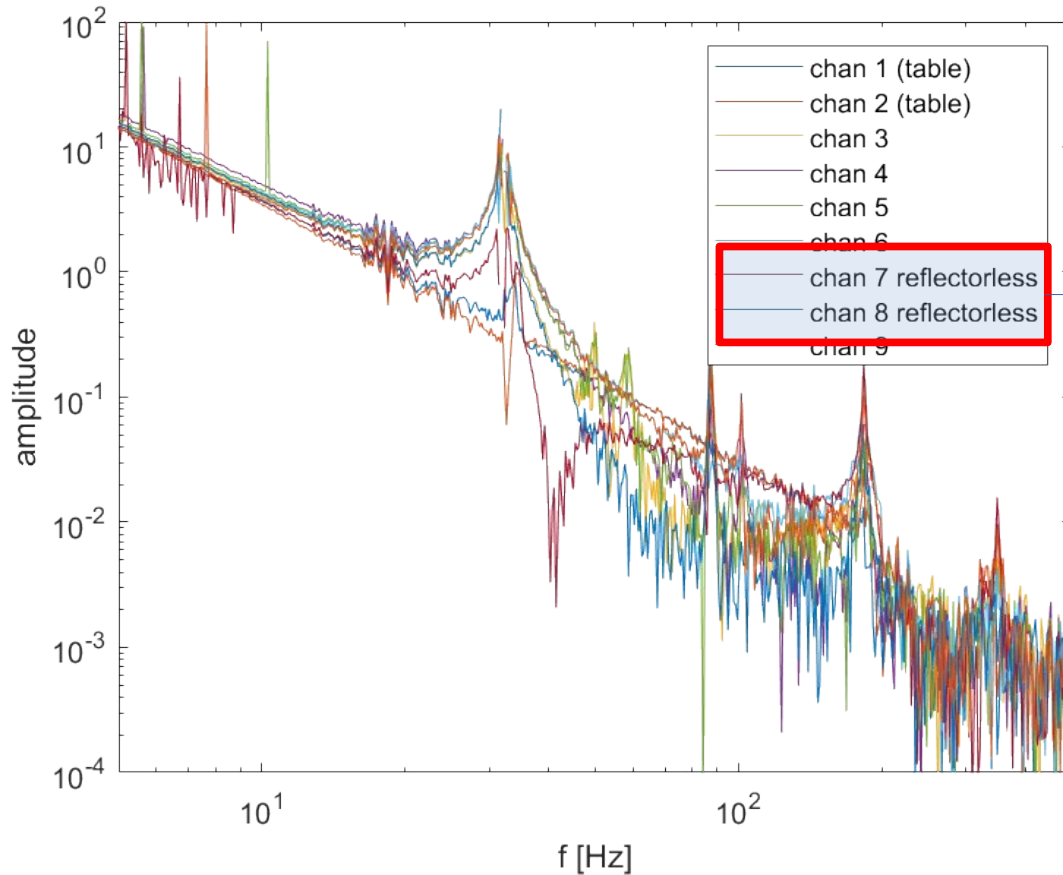
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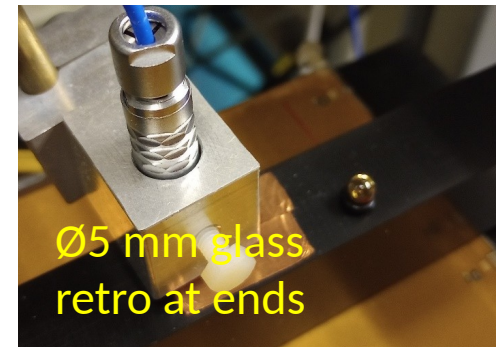


**Time line: building ready, new equipment available autumn 2024.
Plasma-based direct bonding process defined, expected in 2025.**

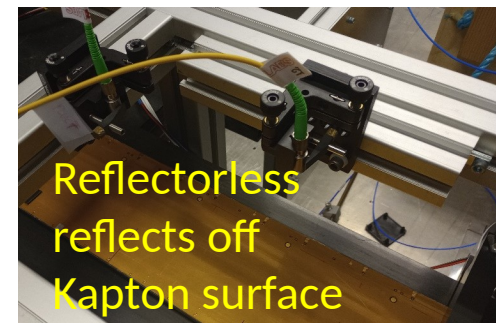
Detailed characterization of mechanical response of tracker elements



FSI system + actuator operational
(despite loss of personpower)



Reflector-less operation works
(AIDA-innova deliverable)



Tests on Kapton successful, other materials soon

Status of WP10: reporting

D #	Deliverable Name	Lead beneficiary	Type	Due Date (in months)
D10.1	Cooling device demonstrators	30 - CSIC	Report	46
D10.2	Hydraulic interconnection technologies	8 - CNRS	Report	43
D10.3	Supercritical CO2 as a refrigerant	25 - NTNU	Report	44
D10.4	Upgraded FSI	41 - UOXF	Report	45

Discussed also “lessons learnt” document on 3D printing with non-standard materials

**Deliverables include reports on main tasks,
Due in months 43-46 (end ‘24, early ‘25)**

Progress/results:

Work proceeding correctly in most nodes; a selection of results shown today
Important: industrial partners actively involved in developments

Practical/organizational:

- Some synergy with I.FAST on additive manufacturing
- Massimo Angeletti joined (busy) WP10 conveners
- An extension of AIDAinnova is likely helpful in several areas